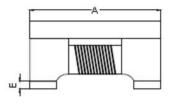
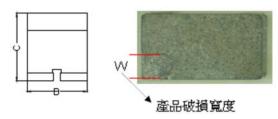


FEATRLRES

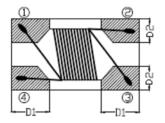
- High common mode impedance at high frequency cause excellent noise suppression performance.
- 100% Lead(Pb) & Halogen-Free and RoHS compliant.

CONFIGRLRATIONS & DIMENSIONS (unit in mm)





當破損面積<5%,產品列入允收品範圍

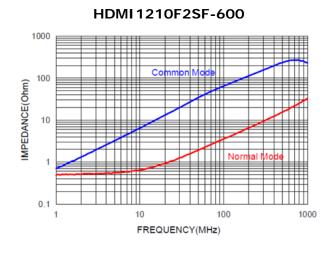


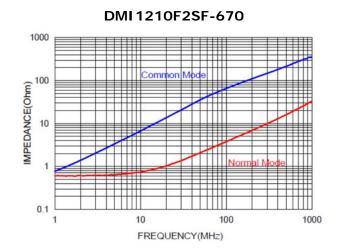
Size	A	В	С	D1	D2	E
1210F2SF	1.2±0.2	1.0±0.2	0.9 max.	0.35±0.1	0.35±0.1	0.03 min.

ELECTRICAL CHARACTERISTICS

Part Number	Impedance (Ω)	Test Frequency (MHz)	DC Resistance (Ω) max.	Rated Current (mA)max.	Rated Volt. (Vdc)max.	Withstand Volt. (Vdc) max.	IR (Ω) min.
HDMI1210F2SF-600T04	60±25%	100	0.30	400	50	125	10M
HDMI1210F2SF-670T04	67±25%	100	0.30	400	50	125	10M
HDMI1210F2SF-900T02	90±25%	100	0.30	250	50	125	10M

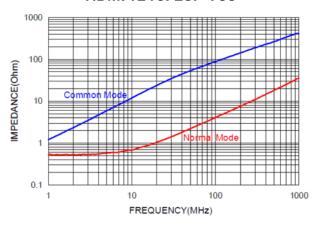
Typical Impedance v.s. Frequency Curve







HDMI1210F2SF-900



Reliability and Test Condition

Item	Performance	Test Condition			
Operating temperature	-40~+125℃ (Including self - temperature rise)				
Storage temperature	110~+40°C,50~60%RH (Product with taping) 240~+125°C (on board)				
Electrical Performance Test					
Inductance	Refer to standard electrical characteristics list.	HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter.			
DCR	Note: to standard decurear diaracteristics list.	CH16502,Agilent33420A Micro-Ohm Meter.			
Saturation Current (Isat)	Approximately∆L30%	Saturation DC Current (Isat) will cause L0 to drop $\triangle L(\%)$			
Heat Rated Current (Irms)	Approximately △T40°C	Heat Rated Current (Irms) will cause the coil temperature rise $\triangle T(^{\circ}C)$. 1.Applied the allowed DC current 2.Temperature measured by digital surface thermometer			
Reliability Test					
		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles) Temperature: 125±2°C (Inductor)			
Life Test		Applied current : rated current			
		Duration: 1000±12hrs Measured at room temperature after placing for 24±2 hrs			
		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles			
Load Humidity		Humidity: 85±2 * R.H,			
		Temperature : 85°C±2°C			
	Appearance : No damage.	Duration: 1000hrs Min. with 100% rated current			
Moisture Resistance	Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Measured at room temperature after placing for 24±2 hrs Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles 1. Baked at50℃ for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs. 3. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs, keep at 25℃ for 2 hrs then keep at -10℃ for 3 hrs 4. Keep at 25℃ 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.			



Thermal shock		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Condition for 1 cycle Step1: -40±2°C 30±5min Step2: 25±2°C ≤0.5min Step3: 125±2°C 30±5min Number of cycles: 500 Measured at room temperature after placing for 24±2 hrs
Vibration		Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes Equipment: Vibration checker Total Amplitude:1.52mm±10% Testing Time: 12 hours(20 minutes, 12 cycles each of 3 orientations).
Bending		Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm Bending depth: >=0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.
Shock	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Type Peak value (g's) Normal duration (D) (ms) Wave form Velocity change (Vi)ft/sec SMD 50 11 Half-sine 11.3 Lead 50 11 Half-sine 11.3
Solder ability	More than 95% of the terminal electrode should be covered with solder.	Preheat: 150°C, 60sec.₀ Solder: Sn96.5% Ag3% Cu0.5% Temperature: 245±5°C ∘ Flux for lead free: Rosin. 9.5% ∘ Dip time: 4±1sec ∘ Depth: completely cover the termination
Resistance to Soldering Heat		Depth: completely cover the termination Temperature (°C) Time(s) Temperature ramp/immersion and emersion rate
Terminal Strength	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value e	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a force(>0805:1kg , <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.

Note: When there are questions concerning measurement result: measurement shall be made after 48 ± 2 hours of recovery under the standard condition.